

PATENT ASSIGNMENT

Electronic Version v1.1

Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
Chin-Sung Lin	06/09/2010
Li-Hua Lin	06/09/2010
Yu-Yu Lin	06/09/2010
RECEIVING PARTY DATA	
Name:	Taiwan Semiconductor Manufacturing Company, Ltd.
Street Address:	No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300-77
Name:	Global Unichip Corp.
Street Address:	No. 10, Li-Hsin 6th Road, Science Park
City:	Hsin-Chu
State/Country:	TAIWAN
Postal Code:	300
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	12814102
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REEL: 024786 FRAME: 0194

ATTORNEY DOCKET NUMBER:	TSM10-0007
NAME OF SUBMITTER:	Michelle Hatcher
Total Attachments: 1 source=TSM10-0007 Assignment#page1.tif	

ATTORNEY DOCKET NO.
TSM10-0007

ASSIGNMENT

WHEREAS, I, the undersigned inventor (or one of the undersigned joint inventors), of residence as listed, having invented certain new and useful improvements as below entitled, for which application for United States Letters Patent is made, the said application having been executed on the date set forth below; and

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd. (TSMC), a corporation organized and existing under the laws of Taiwan, the Republic of China, with its principal office at No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C., and Global Unichip Corp. (GUC), a corporation organized and existing under the laws of Taiwan, the Republic of China, with its principal office at No. 10, Li-Hsin 6th Road, Hsinchu Science Park, Hsinchu City 300, Taiwan, R.O.C., are desirous of acquiring my entire right, title and interest in and to the said invention, and to the said application and any Letters Patent that may issue thereon in the United States and all other countries throughout the world;

NOW, THEREFORE, for good and valuable consideration, the receipt of which is hereby acknowledged, I hereby sell and assign to the said TSMC and GUC, their successors and assigns, my entire right, title and interest in and to the said invention and in to the said application and all patents which may be granted therefor, and all divisions, reissues, substitutions, continuations, and extensions thereof; and I hereby authorize and request the Commissioner for Patents to issue all patents for said invention, or patent resulting therefrom, insofar as my interest is concerned, to the said TSMC and GUC, as assignees of my entire right, title and interest. I declare that I have not executed and will not execute any agreement in conflict herewith.

I also hereby sell and assign to TSMC and GUC, their successors and assigns, my foreign rights to the invention disclosed in said application, in all countries of the world, including, but not limited to, the right to file applications and obtain patents under the terms of the International Convention for the Protection of Industrial Property, and of the European Patent Convention, and further agree to execute any and all patent applications, assignments, affidavits, and any other papers in connection therewith necessary to perfect such patent rights.

I hereby further agree that I will communicate to said TSMC and GUC, or to their successors, assigns, and legal representatives, any facts known to me respecting said invention or the file history thereof, and at the expense of said assignee companies, testify in any legal proceedings, sign all lawful papers, execute all divisional, continuation, reissue and substitute applications, make all lawful oaths, and generally do everything possible to aid said TSMC and GUC, their successors, assigns and nominees to obtain and enforce proper patent protection for said invention in all countries.

IN WITNESS WHEREOF, I hereunto set my hand and seal this day and year;

TITLE OF INVENTION	Package Substrate			
SIGNATURE OF INVENTOR AND NAME	<i>Chin-Sung Lin</i> Chin-Sung Lin	<i>Li-Hua Lin</i> Li-Hua Lin	<i>Lin, Yu-Yu</i> Yu-Yu Lin	
DATE	<i>2010/6/9</i>	<i>2010/6/9</i>	<i>2010/6/9</i>	
RESIDENCE (City, County, State)	Banqiao City, Taiwan	Kaohsiung City, Taiwan	Wujie Township, Taiwan	

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RECORDED: 08/04/2010

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